What’s New?

Program Chair: Steve Miller, NetApp, scm@netapp.com
Program Co-Chair: Jay Fleischman, AMD, jay.fleischman@amd.com

Sunday June 22
5 PM Registration, Dinner and Keynote Presentation, 8:00 PM – 9:15 PM

"The Future is Parallel: What’s a programmer to do?"
Guy Steele, Sun Microsystems, guy.steele@sun.com

Keynote Chair Jim Hughes, Sun, james.hughes@sun.com

Monday June 23
Session 1: Intelligent Networks
8:30 AM – 12:00 noon
1.1 OptiPlanet–Global Computing Via Light Paths
Jason Leigh, Univ of Illinois, spiff@uic.edu
1.2 Global Envir for Network Investigations
Chip Elliott, BBN Technologies, celliot@bn.com
1.3 Network Evolution: Tech & Applications
Charles Kalmanek, AT&T Labs, crk@research.att.com
1.4 Military Communications & Networking
Kenneth Young, Telcordia, key@research.telcordia.com

Session 2: Next Gen Database Systems
1:00 PM – 4:30 PM
2.1 Blue Gene
Todd Takken, IBM, takken@us.ibm.com
2.2 Super Computing & Mainstream Components
Richard Kaufmann, HP, richard.kaufmann@hp.com
2.3 Roadrunner-Heterogeneous Supercomputing
John Morrison, Los Alamos National Laboratory, jfm@lanl.gov
2.4 Programming for Super Parallel Computing
Koh Hotta, Fujitsu, hotta@jp.fujitsu.com

Session 3: Cognitive Computing & User I/Fs
8:00 PM – 10:15 PM
3.1 Data Center Management User Interface
Kostadis Roussos, NetApp, kostadis.roussos@netapp.com
3.2 Computers for Cognition
Richard Lethin, Reservoir Labs, lethin@reservoir.com
3.3 I/F Design – The Good, Bad & Ugly
Mark Anspach, HP, mark.anspach@hp.com

Tuesday June 24
Session 4: Displays & Packaging
8:30 AM – 12:00 noon
4.1 System LSI for Digital Broadcasting Apps
Jiro Naganuma, NTT Cyber Space Lab, naganuma.jiro@lab.ntt.co.jp
4.2 Electronic Paper Network System
Reiji Hattori, Kyushu University, hattori@ed.kyushu-u.ac.jp
4.3 Organic Electronics on Plastic Films
Jiro Kasahara, Sony, jiro.kasahara@jp.sony.com
4.4 Multi-layer Stacked Devices Fabrication
Nobuaki Miyakawa, Honda Research Inst., miyakawa@jp.honda-ri.com

Session 5: Embedded Systems & Apps
8:00 PM – 10:15 PM
5.1 Multi-threaded Multi-core Embedded Systems
Kevin D. Kissell, Paralogos S.A.R.L, kevink@paralogos.com
5.2 MIPS 74K 1GHz+
Jack Brown, MIPS, jackb@mips.com
5.3 Skyplex Satellite Terminal Design
Peter Maurutshke, Global Comm. & Service, pmrm@cosy.sbg.ac.at
5.4 European Research-Embedded Systems
Mario Vinsani, ERIX, Mario.vinsani@tiscali.it

Wednesday June 25
Session 6: Future Technologies
8:30 AM – 12:00 noon
6.1 Nanoelectronics Research Challenges
Jeff Welser, Nanoelectronics Research Inst., jwels@src.org
6.2 Carbon-based Electronics
Shalom Wind, Columbia University, sw2128@columbia.edu
6.3 Quantum Computing
Matthias Steffen, IBM, msteffe@us.ibm.com
6.4 Spintronics
Russell Cowburn, Imperial College London, r.cowburn@imperial.ac.uk

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